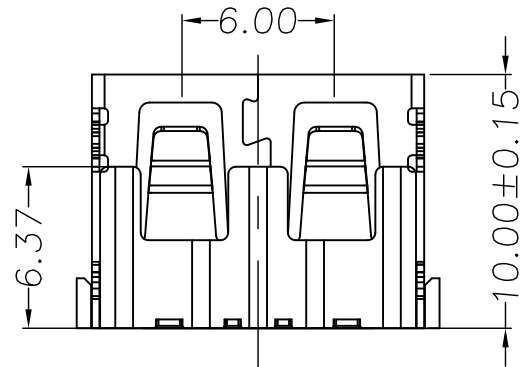
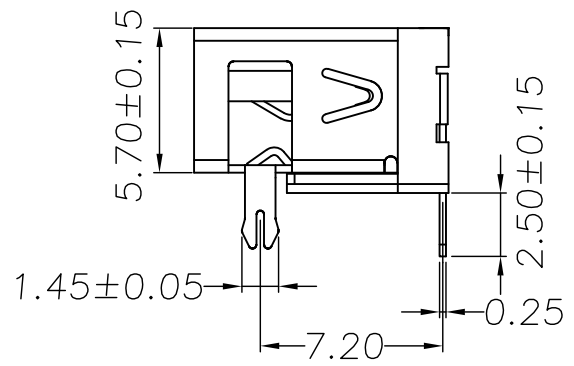
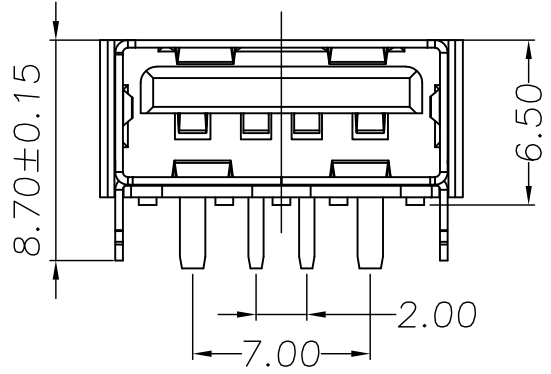
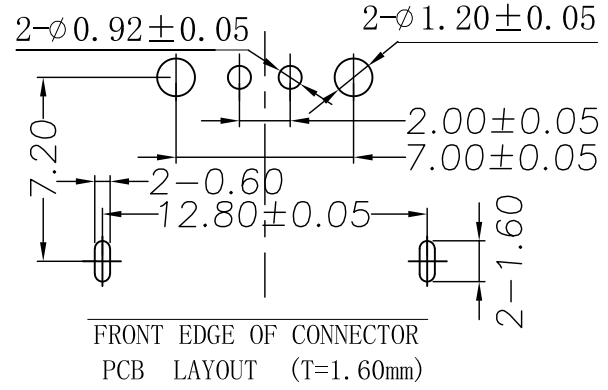
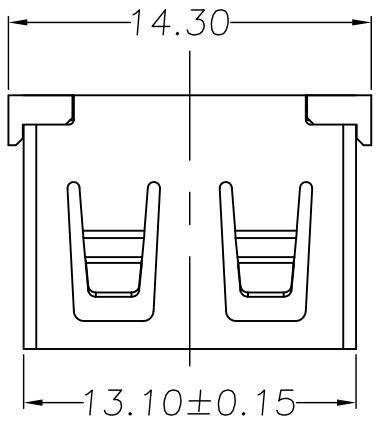


更改 REV	註釋內容 MODIFICATION
A	ECXXXXX



Note:

1. Material:
  - 1.1, Housing: High temperature thermoplastic with/black G/F, UL94v-0
  - 1.2, Contact: copper alloy, t=0.25mm
  - 1.3, Shell: copper/Ferroalloy alloy, t=0.30mm
2. Specification:
  - 2.1, Current rating: 5A Max.
  - 2.2, Dielectric withstanding voltage: 100 V(ac) for 1 min.
  - 2.3, Contact resistance: 30 mΩ Max.
  - 2.4, Insulation resistance: 100 MΩ Min.
  - 2.5, Total mating force: 3.57 Kgf Max.
  - 2.6, Total unmating force: 1.0 Kgf Min.
3. Finish:
  - 3.1, Contact: Plated Golg in Mating Area: Tin On Solder Talls  
Shell: Nickel Plating
4. Environmental:
  - 4.1, Temperature range: -55° C~85° C

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X± 0.50	X*± 5°	
.X± 0.30	.X*± 2°	
.XX± 0.20	.XX*± 1°	名稱(TITLE) USB2.0 AF 10.0 H:6.5mm無卷邊大電流
單位(UNIT) mm	料號(PART NO.) 7USB2-F0-A002	圖號(DWG NO.) 7USB2-F0-A002
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)
		比例 SCALE 1:1
		張數 SHEET 1/1
		圖號 REV A

